# Ultra Low I<sub>q</sub> 350 mA LDO Regulator

The NCV8774 is a 350 mA LDO regulator. Its robustness allows NCV8774 to be used in severe automotive environments. Ultra low quiescent current as low as  $18\,\mu\text{A}$  typical makes it suitable for applications permanently connected to battery requiring ultra low quiescent current with or without load. This feature is especially critical when modules remain in active mode when ignition is off. The NCV8774 contains protection functions as current limit, thermal shutdown and reverse output current protection.

#### **Features**

- Output Voltage Options: 3.3 V and 5 V
- Output Voltage Accuracy: ±1.5% (T<sub>J</sub> = 25°C to 125°C)
- Output Current up to 350 mA
- Ultra Low Quiescent Current: typ 18 μA (max 23 μA)
- Very Wide Range of Cout and ESR Values for Stability
- Wide Input Voltage Operation Range: up to 40 V
- Protection Features
  - Current Limitation
  - Thermal Shutdown
- These are Pb-Free Devices

## **Typical Applications**

- Body Control Module
- Instruments and Clusters
- Occupant Protection and Comfort
- Powertrain

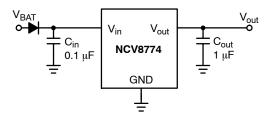


Figure 1. Typical Application Schematic



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## MARKING DIAGRAM



DPAK-3 DT SUFFIX CASE 369C



xx = Voltage Option A = Assembly Location

WL, L = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

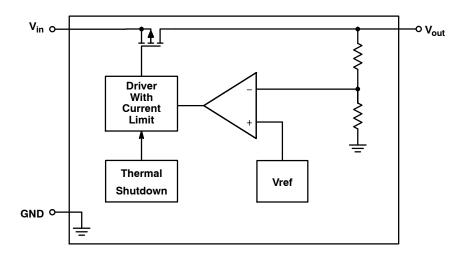


Figure 2. Simplified Block Diagram

## **PIN CONNECTIONS**

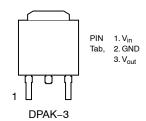


Figure 3. Pin Connections

## **PIN FUNCTION DESCRIPTION**

Pin No.	Pin Name	Description		
1	$V_{in}$	Positive Power Supply Input. Connect 0.1 μF capacitor to ground.		
2, TAB	GND	Power Supply Ground.		
3	V <sub>out</sub>	Regulated Output Voltage. Connect 1 $\mu F$ capacitor with ESR < 100 $\Omega$ to ground.		

#### **ABSOLUTE MAXIMUM RATINGS**

Rati	Symbol	Min	Max	Unit	
Input Voltage (Note 1)	DC Transient, t < 100 ms	V <sub>in</sub>	-0.3 -	40 45	V
Input Current		l <sub>in</sub>	-5	-	mA
Output Voltage (Note 2)		V <sub>out</sub>	-0.3	5.5	V
Output Current		I <sub>out</sub>	-3	Current Limited	mA
Junction Temperature		$T_{J}$	-40	150	°C
Storage Temperature		T <sub>STG</sub>	-55	150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 2. 5.5 V or  $(V_{in} + 0.3 \text{ V})$  (whichever is lower).

#### **ESD CAPABILITY** (Note 3)

Rating	Symbol	Min	Max	Unit
ESD Capability, Human Body Model	ESD <sub>HBM</sub>	-2	2	kV
ESD Capability, Machine Model	ESD <sub>MM</sub>	-200	200	V
ESD Capability, Charged Device Model	ESD <sub>CDM</sub>	-1	1	kV

- 3. This device series incorporates ESD protection and is tested by the following methods:
  - ESD Human Body Model tested per AEC-Q100-002 (JS-001-2010)
  - ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115)
  - ESD Charge Device Model tested per AEC-Q100-011 (EIA/JESD22-C101)

#### LEAD SOLDERING TEMPERATURE AND MSL (Note 4)

Rating	Symbol	Min	Max	Unit
Moisture Sensitivity Level DPAK-3	MSL	-	1	-
Lead Temperature Soldering Reflow (SMD Styles Only), Pb-Free Versions		-	265 peak	°C

<sup>4.</sup> For more information, please refer to our Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### THERMAL CHARACTERISTICS (Note 5)

Rating	Symbol	Value	Unit
Thermal Characteristics, DPAK-3			°C/W
Thermal Resistance, Junction-to-Air (Note 6)	$R_{\theta JA}$	56	
Thermal Reference, Junction-to-Case (Note 6)	$R_{\Psi JC}$	8.4	

- 5. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 6. Values based on copper area of 645 mm<sup>2</sup> (or 1 in<sup>2</sup>) of 1 oz copper thickness and FR4 PCB substrate.

## **RECOMMENDED OPERATING RANGE** (Note 7)

Rating		Min	Max	Unit
Input Voltage (Note 8)	V <sub>in</sub>	4.5	40	V
Junction Temperature		-40	150	°C

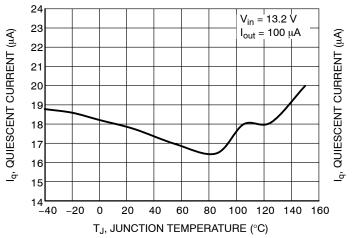
- 7. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 8. Minimum  $V_{in}$  = 4.5 V or  $(V_{out} + V_{DO})$ , whichever is higher.

**ELECTRICAL CHARACTERISTICS**  $V_{in}$  = 13.2 V,  $C_{in}$  = 0.1  $\mu\text{F}$ ,  $C_{out}$  = 1  $\mu\text{F}$ , for typical values  $T_J$  = 25°C, for min/max values  $T_J = -40^{\circ}C$  to 150°C; unless otherwise noted. (Notes 9 and 10)

Parameter		Test Conditions	Symbol	Min	Тур	Max	Unit
REGULATOR OUTPUT						•	
Output Voltage (Accuracy %)	3.3 V 5.0 V	$T_J$ = 25 °C to 125 °C $V_{in}$ = 4.5 V to 16 V, $I_{out}$ = 0.1 mA to 200 mA $V_{in}$ = 5.575 V to 16 V, $I_{out}$ = 0.1 mA to 200 mA	V <sub>out</sub>	3.2505 4.925 (-1.5 %)	3.3 5.0	3.3495 5.075 (+1.5%)	V
		$V_{in}$ = 4.5 V to 40 V, $I_{out}$ = 0.1 mA to 200 mA $V_{in}$ = 4.5 V to 16 V, $I_{out}$ = 0.1 mA to 350 mA $V_{in}$ = 5.6 V to 40 V, $I_{out}$ = 0.1 mA to 200 mA $V_{in}$ = 5.975 V to 16 V, $I_{out}$ = 0.1 mA to 350 mA	V <sub>out</sub>	3.234 3.234 4.9 4.9 (-2 %)	3.3 3.3 5.0 5.0	3.366 3.366 5.1 5.1 (+2%)	V
Output Voltage (Accuracy %)	3.3 V 5.0 V	$T_J = -40^{\circ}C$ to 125°C $V_{in} = 4.5$ V to 28 V, $I_{out} = 0$ mA to 350 mA $V_{in} = 5.975$ V to 28 V, $I_{out} = 0$ mA to 350 mA	V <sub>out</sub>	3.234 4.9 (-2 %)	3.3 5.0	3.366 5.1 (+2%)	V
	3.3 V 5.0 V	V <sub>in</sub> = 4.5 V to 28 V, I <sub>out</sub> = 5 mA V <sub>in</sub> = 6 V to 28 V, I <sub>out</sub> = 5 mA	Reg <sub>line</sub>	-20	0	20	mV
Load Regulation		I <sub>out</sub> = 0.1 mA to 350 mA	Reg <sub>load</sub>	-35	0	35	mV
Dropout Voltage (Note 11)	5.0 V	I <sub>out</sub> = 200 mA I <sub>out</sub> = 350 mA	V <sub>DO</sub>	- -	250 440	500 875	mV
QUIESCENT CURRENT							
Quiescent Current (I <sub>q</sub> = I <sub>in</sub> - I <sub>out</sub> )		$I_{out} = 0.1 \text{ mA, } T_J = 25^{\circ}\text{C}$ $I_{out} = 0.1 \text{ mA to } 350 \text{ mA, } T_J \leq 125^{\circ}\text{C}$	Iq	- -	18 -	22 23	μΑ
CURRENT LIMIT PROTECTION							
Current Limit		V <sub>out</sub> = 0.96 x V <sub>out_nom</sub>	I <sub>LIM</sub>	400	-	1100	mA
Short Circuit Current Limit		$V_{out} = 0 V$	I <sub>SC</sub>	400	-	1100	mA
PSRR							
Power Supply Ripple Rejection (Not	e 12)	f = 100 Hz, 0.5 V <sub>pp</sub>	PSRR	_	54	-	dB
THERMAL SHUTDOWN							
Thermal Shutdown Temperature (Note 12)			T <sub>SD</sub>	150	175	195	°C
Thermal Shutdown Hysteresis (Note 12)			T <sub>SH</sub>	-	25	-	°C
		INCC and ADDI ICATION INCODMATION for C	, ,				

Refer to ABSOLUTE MAXIMUM RATINGS and APPLICATION INFORMATION for Safe Operating Area.
 Performance guaranteed over the indicated operating temperature range by design and/or characterization tested at T<sub>A</sub> ≈ T<sub>J</sub>. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
 Measured when output voltage falls 100 mV below the regulated voltage at V<sub>in</sub> = 13.2 V.
 Values based on design and/or characterization.

## **TYPICAL CHARACTERISTICS**



100  $I_{out} = 100 \,\mu\text{A}$  $T_J = 25^{\circ}C$ 80 60 40 20 0 5 10 15 20 25 30 35 40 0 V<sub>in</sub>, INPUT VOLTAGE (V)

Figure 4. Quiescent Current vs. Temperature

Figure 5. Quiescent Current vs. Input Voltage

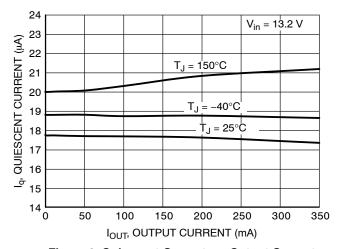


Figure 6. Quiescent Current vs. Output Current

3.36

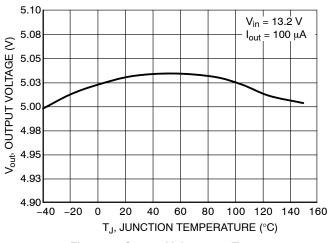


Figure 7. Output Voltage vs. Temperature (5 V Option)

Figure 8. Output Voltage vs. Temperature (3.3 V Option)

V<sub>in</sub> = 13.2 V

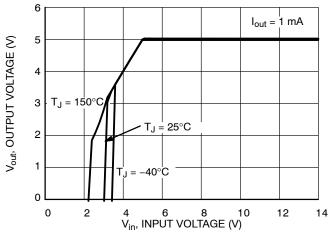


Figure 9. Output Voltage vs. Input Voltage (5 V Option)

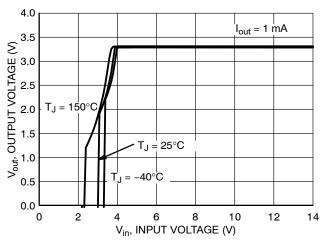


Figure 10. Output Voltage vs. Input Voltage (3.3 V Option)

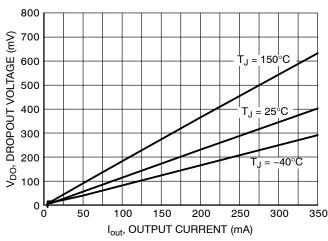


Figure 11. Dropout vs. Output Current (5 V Option)

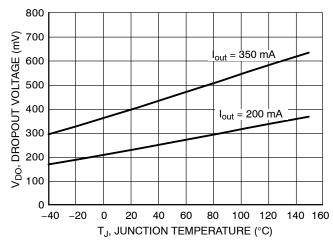


Figure 12. Dropout vs. Temperature (5 V Option)

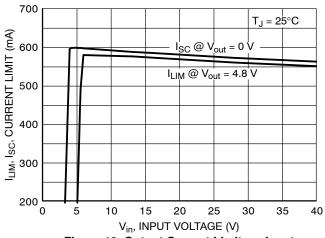


Figure 13. Output Current Limit vs. Input Voltage (5 V Option)

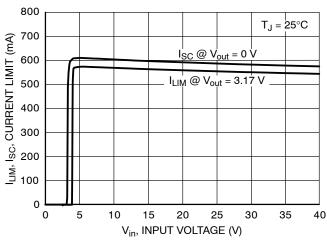


Figure 14. Output Current Limit vs. Input Voltage (3.3 V Option)

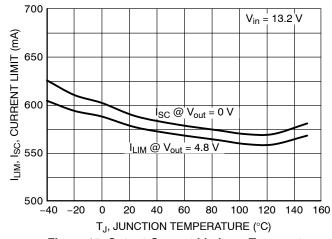


Figure 15. Output Current Limit vs. Temperature (5 V Option)

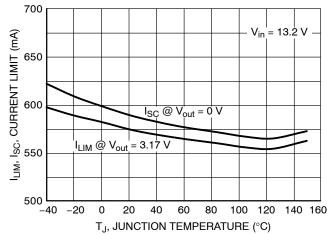


Figure 16. Output Current Limit vs. Temperature (3.3 V Option)

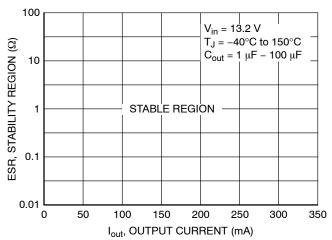
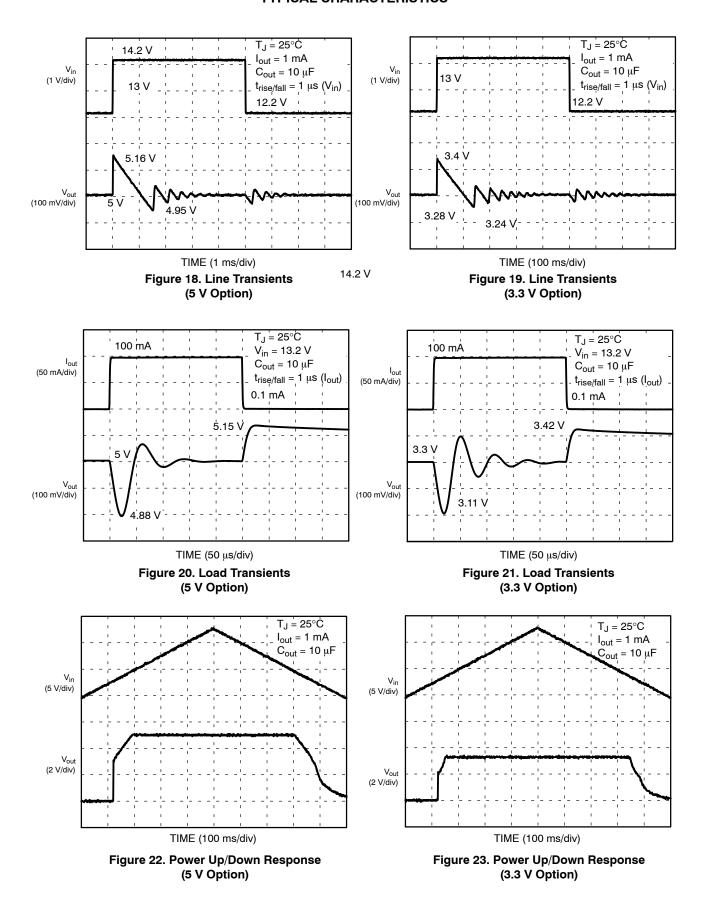


Figure 17. C<sub>out</sub> ESR Stability Region vs. Output Current



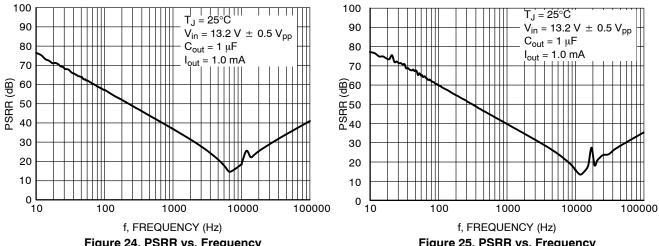


Figure 24. PSRR vs. Frequency (5 V Option)

Figure 25. PSRR vs. Frequency (3.3 V Option)

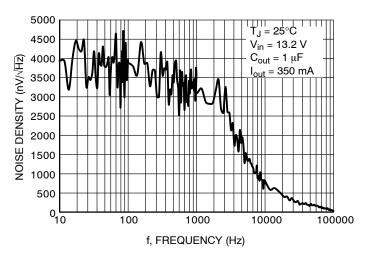


Figure 26. Noise vs. Frequency

#### **DEFINITIONS**

#### General

All measurements are performed using short pulse low duty cycle techniques to maintain junction temperature as close as possible to ambient temperature.

#### **Output voltage**

The output voltage parameter is defined for specific temperature, input voltage and output current values or specified over Line, Load and Temperature ranges.

## **Line Regulation**

The change in output voltage for a change in input voltage measured for specific output current over operating ambient temperature range.

#### **Load Regulation**

The change in output voltage for a change in output current measured for specific input voltage over operating ambient temperature range.

## **Dropout Voltage**

The input to output differential at which the regulator output no longer maintains regulation against further reductions in input voltage. It is measured when the output drops 100 mV below its nominal value. The junction temperature, load current, and minimum input supply requirements affect the dropout level.

#### **Quiescent and Disable Currents**

Quiescent Current  $(I_q)$  is the difference between the input current (measured through the LDO input pin) and the output load current.

#### **Current Limit and Short Circuit Current Limit**

Current Limit is value of output current by which output voltage drops below 96% of its nominal value. Short Circuit Current Limit is output current value measured with output of the regulator shorted to ground.

#### **PSRR**

Power Supply Rejection Ratio is defined as ratio of output voltage and input voltage ripple. It is measured in decibels (dB).

## **Line Transient Response**

Typical output voltage overshoot and undershoot response when the input voltage is excited with a given slope.

### **Load Transient Response**

Typical output voltage overshoot and undershoot response when the output current is excited with a given slope between low-load and high-load conditions.

#### **Thermal Protection**

Internal thermal shutdown circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated at typically 175°C, the regulator turns off. This feature is provided to prevent failures from accidental overheating.

#### **Maximum Package Power Dissipation**

The power dissipation level is maximum allowed power dissipation for particular package or power dissipation at which the junction temperature reaches its maximum operating value, whichever is lower.

#### **APPLICATIONS INFORMATION**

The NCV8774 regulator is self-protected with internal thermal shutdown and internal current limit. Typical characteristics are shown in Figures 4 to 26.

#### Input Decoupling (Cin)

A ceramic or tantalum 0.1  $\mu F$  capacitor is recommended and should be connected close to the NCV8774 package. Higher capacitance and lower ESR will improve the overall line and load transient response.

If extremely fast input voltage transients are expected then appropriate input filter must be used in order to decrease rising and/or falling edges below 50 V/ $\mu$ s for proper operation. The filter can be composed of several capacitors in parallel.

## Output Decoupling (Cout)

The NCV8774 is a stable component and does not require a minimum Equivalent Series Resistance (ESR) for the output capacitor. Stability region of ESR vs Output Current is shown in Figure 17. The minimum output decoupling value is 1  $\mu F$  and can be augmented to fulfill stringent load transient requirements. The regulator works with ceramic chip capacitors as well as tantalum devices. Larger values improve noise rejection and load regulation transient response.

#### **Thermal Considerations**

As power in the NCV8774 increases, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and the ambient temperature affect the rate of junction temperature rise for the part. When the NCV8774 has good thermal conductivity through the PCB, the junction temperature will be relatively low with high power applications. The maximum dissipation the NCV8774 can handle is given by:

$$P_{D(max)} = \frac{\left[T_{J(max)} - T_{A}\right]}{R_{\theta JA}}$$
 (eq. 1)

Since  $T_J$  is not recommended to exceed 150°C, then the NCV8774 soldered on 645 mm², 1 oz copper area, FR4 can dissipate up to 2.35 W when the ambient temperature ( $T_A$ ) is 25°C. See Figure 27 for  $R_{\theta JA}$  versus PCB area. The power dissipated by the NCV8774 can be calculated from the following equations:

$$P_{D} = V_{in}(I_{q}@I_{out}) + I_{out}(V_{in} - V_{out}) \qquad (eq. 2)$$

or

$$V_{in(max)} = \frac{P_{D(max)} + (V_{out} \times I_{out})}{I_{out} + I_{q}}$$
 (eq. 3)

NOTE: Items containing  $I_q$  can be neglected if  $I_{out} >> I_q$ .

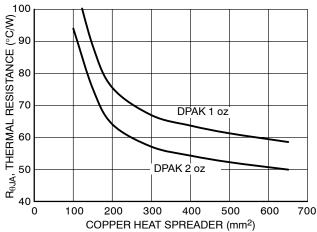


Figure 27. Thermal Resistance vs. PCB Copper Area

#### Hints

 $V_{\rm in}$  and GND printed circuit board traces should be as wide as possible. When the impedance of these traces is high, there is a chance to pick up noise or cause the regulator to malfunction. Place external components, especially the output capacitor, as close as possible to the NCV8774 and make traces as short as possible.

#### ORDERING INFORMATION

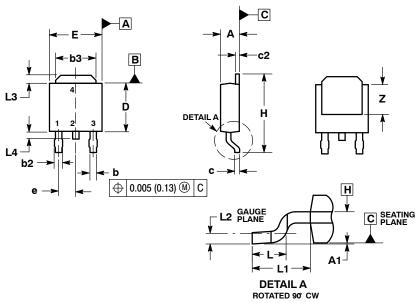
Device	Output Voltage	Marking	Package	Shipping <sup>†</sup>
NCV8774DT50RKG	5.0 V	877450G	DPAK-3 (Pb-Free)	2500 / Tape & Reel
NCV8774DT33RKG	3.3 V	877433G	DPAK-3 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

## **DPAK (SINGLE GAUGE)**

CASE 369C ISSUE D



#### NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS D3, L3 and Z.

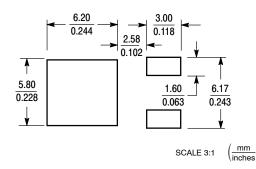
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

  5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108	REF	2.74 REF	
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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